

**Specifications** 

Insulation Resistance



ESD SMD Comm X7R, Ceramic, 0.033 uF, 10%, 50 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 0805, 0.6 mm



General Information	
Series	ESD SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	13 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0805
L	2mm +/-0.3mm
W	1.25mm +/-0.3mm
Т	1mm +/-0.20mm
S	0.6mm MIN
В	0.5mm +/-0.25mm

Capacitance	0.033 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	50 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5%1kHz1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee

Time is 1000 Hours 30.303 GOhms

Packaging Specifications	
Packaging	Bulk, Bag
Packaging Quantity	1

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